## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## HIGH DENSITY SEMICONDUCTOR PACKAGE

the	specification of whic	h			
_X	is attached hereto.				
	was filed on				
	as Application Seri	al No	and was amended on		·
ap for	ecification, including to I acknowledge the plication in accordanc I hereby claim fore plication(s) for paten	he claims, as amended duty to disclose informate with Title 37, Code of the disclose information of the disclose the discl	nd understand the contend by any amendment referred to material to of Federal Regulations, § 1. der Title 35, United States Cate listed below and have ficate having a filing date be	ed to above. the patents 56(a). Code, § 119 also identifi	ability of this of any foreign ed below any
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
	91125100	Taiwan, R.O.C.	2002/10/25	X	
tra	I hereby appoint the following attorney(s) insact all business in the Patent and Tradema  Belinda Lee (Reg. No. 46,863) Jiawei Huang (Reg. No. 43,330) Charles C.H. Wu (Reg. No. 39,081)  SEND CORRESPONDENCE TO:  JIANQ CHYUN Intellectual Property Office 7F1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C. TEL: 886-2-2369 2800 FAX: 886-2-2369 7233		nark Office connected therev  3) Charles Liu  0)		
			DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
				Belinda Lee	

## COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature:

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